

We are happy to inform you that Materials Transactions (The Japan Institute of Metals) will publish a special issue on "New Functions and Properties of Engineering Materials Created by Designing and Processing" as July 2009. You will find the announcement on the issue and the instruction of preparation in following page.

Announcement

Materials processing technology has significantly contributed to the success of the manufacturing industry, and the advanced researches for creating novel functions and properties by materials designing and processing are steadily progressing. This special issue covers novel functions and properties of metallic, ceramic, polymer and composite materials produced by microstructural control and alignment. It also presents the current status of various techniques such as 3-D imaging, sensing, and multi-scale simulation used for materials designing and processing. We expect to receive original papers related to the presentations that will be made at ISAEM2008 (4th International Symposium on Designing, Processing and Properties of Advanced Engineering Materials), which will be held in November, but not restricted to the presented papers at ISAEM2008.

http://www.sendai.kopas.co.jp/METAL/PUBS/E/e_info.html#69

Topics: materials processing, 3-D imaging, materials simulation, microstructural control, multi-scale modeling, severe plastic deformation, composite materials, biomedical materials, ceramics, polymer materials

Instruction of preparation

Bylaws for Contribution to Materials Transactions
<http://www.sendai.kopas.co.jp/METAL/rule.html>

Manuscript Instructions
<http://www.sendai.kopas.co.jp/METAL/point.html>

Application form
<http://wwwsoc.nii.ac.jp/jim/kaigaieentry.htm>

We would be very pleased if you would contribute an original paper (Regular Article) to the issue.

Contributors will bear part of the cost for publication. Contributors will be presented 50 reprints free.

Please register in the Application Form Page if you will contribute your paper.

Manuscripts due is January 6, 2009.

Hoping to hear from you not later than Novemebr 1, 2008.